2SB1073

Silicon PNP epitaxial planar type

For low-frequency amplification

■ Features

- Low collector-emitter saturation voltage V_{CE(sat)}
- ullet Large peak collector current I_{CP}
- Mini Power type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	-30	V	
Collector-emitter voltage (Base open)	V _{CEO}	-20	V	
Emitter-base voltage (Collector open)	V_{EBO}	-7	V	
Collector current	I_C	-4	A	
Peak collector current	I _{CP}	-7	A	
Collector power dissipation *	P _C	1	W	
Junction temperature	T _j	150	°C	
Storage temperature	T _{stg}	-55 to +1 5 0	°C	

Note) *: Print circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion

Unit: mm MiniP3-F1 Package

Marking Symbol: J

■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Peak collector current	I_{CP}	-7	A Marking	Symbol	110		
Collector power dissipation *	P _C	1	W	a X			
function temperature T_i 150 °C							
Storage temperature T _{stg} -55 to +150 °C							
Peak collector current Collector power dissipation * Pc 1 W Junction temperature T _i 150 °C Storage temperature T _{stg} -55 to +150 °C Note) *: Print circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion Electrical Characteristics T _a = 25°C ± 3°C							
Parameter	Symbol		Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emiter open)	V_{CBO}	$I_{\rm C} = -10 \mu$	$A, I_E = 0$	-30			V
Collector-emitter voltage (Base open)	V _{CEO}	I _Q = -1 m/	$A, I_B \neq 0$	-20			V
Emiter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = -10 \mu$	$A, I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -30$	$V, I_E = 0$			- 0.1	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = -7$	$V, I_C = 0$			- 0.1	μΑ
Forward current transfer ratio *1, 2	h _{FE}	$V_{CE} = -2$	$V, I_{C} = -2 A$	120		315	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -3 \text{ A},$	$I_B = -0.1 \text{ A}$		- 0.6	-1.0	V
Transition frequency	f_T	$V_{CB} = -6$	$V, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		120		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = -20$	$V, I_E = 0, f = 1 \text{ MHz}$		40		pF

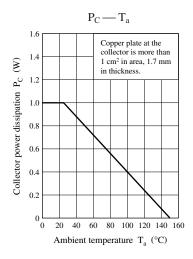
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

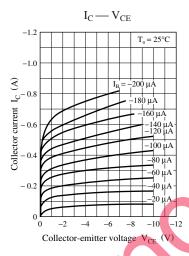
2. *1: Pulse measurement

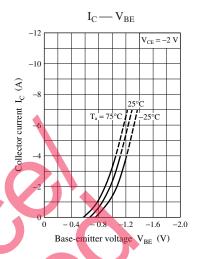
*2: Rank classification

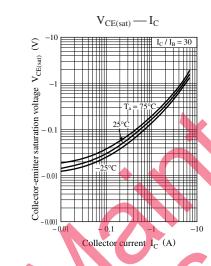
Rank	Q	R
h_{FE}	120 to 205	180 to 315

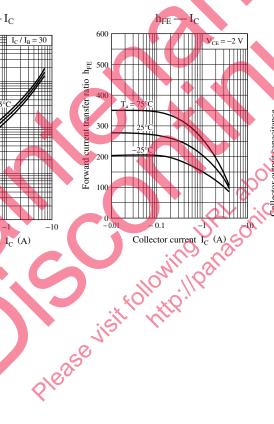
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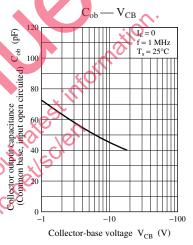












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